



DATE: 3 March, 2023

PCN #: 2618

PCN Title: Qualification of Additional Wafer Source, and Lead Frame Structure and Mold Compound Type Changes for Select Discrete Automotive Products

Dear Customer:

This is an announcement of change(s) to products that are currently being offered by Diodes Incorporated.

We request that you acknowledge receipt of this notification within 30 days of the date of this PCN. If you require samples for evaluation purposes, please make a request immediately. Please refer to the implementation date of this change as it is stated in the attached PCN form. Please contact your local Diodes sales representative to acknowledge receipt of this PCN and for any sample requests.

The changes announced in this PCN will not be implemented earlier than 90 days from the notification date stated in the attached PCN form.

Previously agreed upon customer specific change process requirements or device specific requirements will be addressed separately.

For questions or clarification regarding this PCN, please contact your local Diodes sales representative.

Sincerely,

Diodes Incorporated PCN Team



PRODUCT CHANGE NOTICE**PCN-2618 REV 1**

Notification Date:	Implementation Date:	Product Family:	Change Type:	PCN #:
3 March, 2023	3 June, 2023	Discrete - Automotive	Wafer Fab Material, Assembly Material	2618
TITLE				
Qualification of Additional Wafer Source, Lead Frame Structure, and Mold Compound Type Changes for Select Discrete Automotive Products				
DESCRIPTION OF CHANGE				
<p>This PCN is being issued to notify customers that in order to assure continuity of supply, Diodes Incorporated has qualified Diodes internal BCD (Shanghai) Micro-Electronics Limited (SFAB2) in Shanghai, China as an additional wafer source for select automotive products listed below, and an enhanced lead frame structure and mold compound type for PowerDI-5 packaged products as listed below.</p> <p>Full electrical characterization and high reliability testing has been completed on representative part numbers to ensure no change to device functionality or electrical specifications in the datasheet. Refer to the attached qualification report embedded in this file (to view, download this PCN file then open it with a PDF viewer to see the attached qual report).</p> <p>There will be no change to the Form, Fit, or Function of affected products.</p>				
IMPACT				
No change in datasheet parameters and product performance				
PRODUCTS AFFECTED				
Table 1 – Affected part list to add SFAB2 as additional wafer source Table 2 – Affected part list to add SFAB2 as additional wafer source, and change lead frame and mold compound for PowerDI-5 package				
WEB LINKS				
Manufacturer's Notice:	https://www.diodes.com/quality/product-change-notices/diodes-product-change-notices/			
For More Information Contact:	https://www.diodes.com/about/contact-us/contact-sales/			
Data Sheet:	https://www.diodes.com/catalog/			
DISCLAIMER				
Unless a Diodes Incorporated Sales representative is contacted in writing within 30 days of the posting of this notice, all changes described in this announcement are considered approved.				

Table 1: Affected part list to add SFAB2 as additional wafer source

SBR02U100LPQ-7	SBR1045CTLQ-13	SBR15U100CTLQ-13	SBR3045CTBQ-13	SBR3U40P1Q-7	SBR6100CTLQ-13
SBR02U100LPQ-7B	SBR1045D1Q-13	SBR20M45D1Q-13	SBR30A45CTBQ-13	SBR3U60P1Q-7	SBR660CTLQ-13
SBR0560S1Q-7	SBR10U45D1Q-13	SBR2A40P1Q-7	SBR30A60CTBQ-13		

Table 2: Affected part list to add SFAB2 as additional wafer source, and change lead frame and mold compound for PowerDI-5 package

SBR1045SP5Q-13	SBR10U200P5Q-13	SBR10U45SP5Q-13	SBR12U100P5Q-13	SBR8U60P5Q-13	SBR8U60P5Q-13D
SBR10A45SP5Q-13	SBR10U200P5Q-13D	SBR10U45SP5Q-13D	SBR12U100P5Q-13D		